

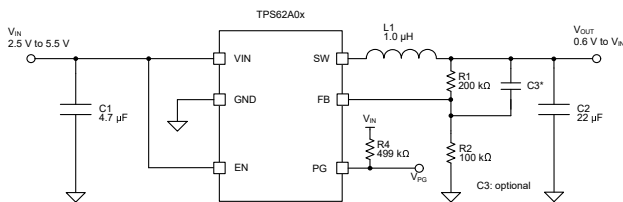
TPS62A0x、TPS62A0xA、TPS62A02Nx、1A および 2A 高効率同期整流降圧コンバータ、SOT-563 および SOT-23 パッケージ

1 特長

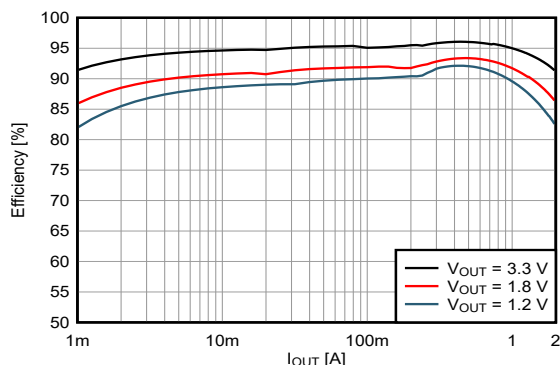
- 入力電圧範囲: 2.5V~5.5V
- 調整可能な出力電圧範囲: 0.6V~ V_{IN}
- 180mΩ/120mΩ 低 $R_{DS(on)}$ スイッチ (1A DRL)
- 100mΩ/67mΩ 低 $R_{DS(on)}$ スイッチ (1A DDC、2A)
- < 23μA の静止電流
- タイミング精度: 1% (0°C~125°C)
- 100% モード動作
- 2.4MHz のスイッチング周波数
- パワーセーブモードまたは PWM オプションが利用可能
- パワーグッド出力ピン (オプション)
- 短絡保護 (HICCUP)
- ソフトスタートアップを内蔵
- アクティブ出力放電
- サーマルシャットダウン保護機能
- TLV62585 (DRL) とピン互換
- TLV62569 (DDC) とピン互換

2 アプリケーション

- セットトップボックス、TV アプリケーション
- IP ネットワークカメラ、多機能プリンタ
- ワイヤレスルータ、ソリッドステートドライブ
- バッテリ駆動アプリケーション
- 汎用 POL (ポイントオブロード) 電源



代表的なアプリケーション



5V_{IN} での効率と出力電流との関係 (TPS62A02x)

3 概要

TPS62A0x デバイスファミリは同期整流降圧型 DC/DC コンバータで、高効率と小型の設計サイズ向けに最適化されています。このデバイスには、最大 2A の出力電流を供給できるスイッチが内蔵されています。中負荷から高負荷では、デバイスはパルス幅変調 (PWM) モードで、2.4MHz のスイッチング周波数で動作します。軽負荷時には、デバイスは自動的にパワーセーブモード (PSM) へ移行し、負荷電流範囲の全体にわたって高い効率を維持します。シャットダウン時には、消費電流も最小限に抑えられます。このデバイスファミリの TPS62A0xA のバリエーションでは、負荷電流範囲全体にわたって強制 PWM で動作します。

TPS62A0x デバイスは、外付けの分圧抵抗によって出力電圧を変更できます。内部のソフトスタート回路により、スタートアップ時の突入電流が制限されます。過電流保護、サーマルシャットダウン保護、パワーグッド (オプション) など、その他の機能も組み込まれています。本デバイスは SOT563 および SOT23-6 パッケージで供給されます。

パッケージ情報

部品番号	パッケージ (1)	パッケージサイズ (2)
TPS62A01x	DRL (SOT-563, 6)	1.60mm × 1.60mm
	DDC (SOT-23, 6)	2.90mm × 2.80mm
TPS62A02x	DRL (SOT-563, 6)	1.60mm × 1.60mm
	DDC (SOT-23, 6)	2.90mm × 2.80mm
TPS62A02Nx	DRL (SOT-563, 6)	1.60mm × 1.60mm

- (1) 詳細については、[セクション 11](#) を参照してください。
- (2) パッケージサイズ (長さ × 幅) は公称値であり、該当する場合はピンも含まれます。

製品情報

部品番号 (1)	動作モード	出力電流	ピン 6
TPS62A01	PSM, PWM	1A	PG
TPS62A01A	FPWM		
TPS62A02	PSM, PWM	2A	OUT
TPS62A02A	FPWM		
TPS62A02N	PSM, PWM		
TPS62A02NA	FPWM		

- (1) 「製品比較」表を参照してください。



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4 Device Comparison Table

Device Number	Output Current	Package	Operation Mode	Pin 6
TPS62A01DRLR	1A	SOT-563, 6	PSM, PWM	PG
TPS62A01ADRLR			FPWM	
TPS62A02DRLR	PSM, PWM		OUT	
TPS62A02ADRLR	FPWM			
TPS62A02NDRLR	PSM, PWM			
TPS62A02NADRLR	FPWM			
TPS62A01PDDCR	1A	SOT-23, 6	PSM, PWM	PG
TPS62A01APDDCR			FPWM	
TPS62A02PDDCR	2A		PSM, PWM	
TPS62A02APDDCR			FPWM	

5 Pin Configuration and Functions

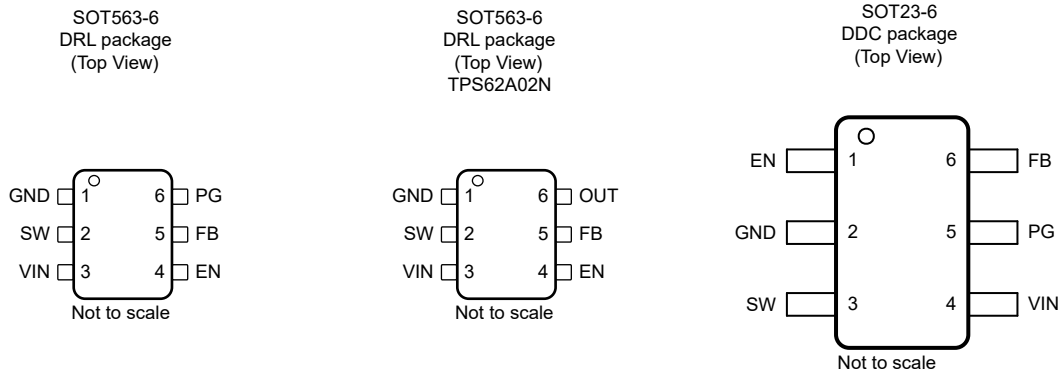


图 5-1. 6-Pin DRL SOT-563 Package (Top View), 6-Pin DDC SOT-23 Package (Top View)

表 5-1. Pin Functions

Name	Pin Number		Type ⁽¹⁾	Description
	SOT563-6	SOT23-6		
EN	4	1	I	Device enable logic input. Logic high enables the device. Logic low disables the device and turns the device into shutdown. Do not leave the pin floating.
FB	5	6	I	Feedback pin for the internal control loop. Connect this pin to an external feedback divider.
GND	1	2	G	Ground pin.
PG	6	5	O	Power-good open-drain output pin. The pullup resistor cannot be connected to any voltage higher than 5.5V. If unused, leave the pin open or connect to GND.
OUT ⁽²⁾		/	I	Output voltage sense pin.
SW	2	3	O	Switch pin connected to the internal FET switches and inductor terminal. Connect the inductor of the output filter to this pin.
VIN	3	4	I	Input voltage pin. Connect the input capacitor as close as possible between V_{IN} and GND.

(1) I = Input, O = Output, G = Ground.

(2) Only for TPS62A0xN versions.

6 Specifications

6.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

		MIN	MAX	UNIT
Pin voltage ⁽²⁾	VIN, EN, PG	-0.3	6.5	V
	SW, DC	-0.3	V _{IN} + 0.3	V
	SW, transient < 10 ns	-3.0	10	V
	FB	-0.3	3	V
T _J	Operating junction temperature	-40	150	°C
T _{stg}	Storage temperature	-55	150	°C

- (1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute Maximum Ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If used outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
- (2) All voltage values are with respect to the network ground terminal.

6.2 ESD Ratings

			VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000	V
		Charged-device model (CDM), per ANSI/ESDA/JEDEC JS-002 ⁽²⁾	±500	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

Over operating junction temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V _{IN}	Input supply voltage range	2.5		5.5	V
V _{OUT}	Output voltage range	0.6		V _{IN}	V
I _{OUT}	Output current range	0		1	A
I _{OUT}	Output current range ⁽¹⁾	0		2	A
L	Effective inductance		1.0		μH
C _{OUT}	Output capacitance	V _{OUT} < 1.2 V	44		μF
C _{OUT}	Output capacitance	1.2 V ≤ V _{OUT} < 1.8 V	22		μF
C _{OUT}	Output capacitance	V _{OUT} ≥ 1.8 V	10		μF
I _{PG}	Power Good input current capability	0		1	mA
T _J	Operating junction temperature	-40		125	°C

- (1) Operating continuously at 2-A with input voltages < 3.3V or at ambient temperatures > 85 °C might result in thermal shutdown, per EVM measurements.

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		TPS62A0x	TPS62A0x	UNIT
		DRL	DDC	
		6 PINS	6 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	157.3	132.1	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	92.2	74.9	°C/W
R _{θJB}	Junction-to-board thermal resistance	45.6	45.5	°C/W
ψ _{JT}	Junction-to-top characterization parameter	4.0	25.5	°C/W

6.4 Thermal Information (続き)

THERMAL METRIC ⁽¹⁾		TPS62A0x	TPS62A0x	UNIT
		DRL	DDC	
		6 PINS	6 PINS	
Ψ_{JB}	Junction-to-board characterization parameter	45.0	45.1	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) report.

6.5 Electrical Characteristics

$T_J = -40^\circ\text{C}$ to $+125^\circ\text{C}$, $V_{IN} = 2.5\text{ V}$ to 5.5 V . Typical values are at $T_J = 25^\circ\text{C}$ and $V_{IN} = 5\text{ V}$ (unless otherwise noted)

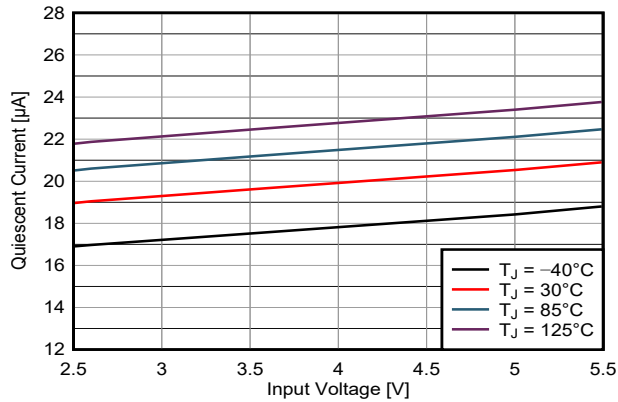
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
SUPPLY						
$I_{Q(VIN)}$	VIN quiescent current	Non-switching; $V_{EN} = \text{High}$; $V_{FB} = 610\text{ mV}$; TPS62A01xDRL		20		μA
$I_{Q(VIN)}$	VIN quiescent current	Non-switching; $V_{EN} = \text{High}$; $V_{FB} = 610\text{ mV}$; TPS62A01xDDC; TPS62A02		23		μA
$I_{SD(VIN)}$	VIN shutdown supply current	$V_{EN} = \text{Low}$		0.01	2	μA
UVLO						
$V_{UVLO(R)}$	VIN UVLO rising threshold	V_{IN} rising	2.3	2.4	2.5	V
$V_{UVLO(F)}$	VIN UVLO falling threshold	V_{IN} falling	2.2	2.3	2.4	V
ENABLE						
$V_{EN(R)}$	EN voltage rising threshold	EN rising; enable switching	1.2			V
$V_{EN(F)}$	EN voltage falling threshold	EN falling, disable switching			0.4	V
$V_{EN(LKG)}$	EN Input leakage current	$V_{EN} = 5\text{ V}$			100	nA
REFERENCE VOLTAGE						
V_{FB}	FB voltage	$T_J = 0^\circ\text{C}$ to 125°C , PWM mode	594	600	606	mV
V_{FB}	FB voltage	PWM mode	591	600	609	mV
$I_{FB(LKG)}$	FB input leakage current	$V_{FB} = 0.6\text{ V}$			100	nA
SWITCHING FREQUENCY						
$f_{SW(FCCM)}$	Switching frequency, FPWM operation	$V_{IN} = 5\text{ V}$; $V_{OUT} = 1.8\text{ V}$		2400		kHz
STARTUP						
	Internal fixed soft-start time	From EN = High to $V_{FB} = 0.56\text{ V}$			1	ms
POWER STAGE						
$R_{DS(on)(HS)}$	High-side MOSFET on-resistance	TPS62A01xDRL; $V_{IN} = 5\text{ V}$		180		m Ω
$R_{DS(on)(LS)}$	Low-side MOSFET on-resistance	TPS62A01xDRL; $V_{IN} = 5\text{ V}$		120		m Ω
$R_{DS(on)(HS)}$	High-side MOSFET on-resistance	$V_{IN} = 5\text{ V}$; TPS62A01xDDC; TPS62A02		100		m Ω
$R_{DS(on)(LS)}$	Low-side MOSFET on-resistance	$V_{IN} = 5\text{ V}$; TPS62A01xDDC; TPS62A02		67		m Ω
OVERCURRENT PROTECTION						
$I_{HS(OC)}$	High-side peak current limit	TPS62A01	1.3	1.8		A
$I_{LS(OC)}$	Low-side valley current limit	TPS62A01		1.8		A
$I_{HS(OC)}$	High-side peak current limit	TPS62A02	2.7	3.4		A
$I_{LS(OC)}$	Low-side valley current limit	TPS62A02xDRL		4.2		A
$I_{LS(OC)}$	Low-side valley current limit	TPS62A02xDDC		3.15		A
POWER GOOD						
V_{PGTH}	Power Good threshold	PG low, FB falling		93.5		%
V_{PGTH}	Power Good threshold	PG high, FB rising		96		%
	PG delay falling			35		μs
	PG delay rising			10		μs
$I_{PG(LKG)}$	PG pin Leakage current when open drain output is high	$V_{PG} = 5\text{ V}$			100	nA
	PG pin output low-level voltage	$I_{PG} = 1\text{ mA}$			400	mV

6.5 Electrical Characteristics (続き)

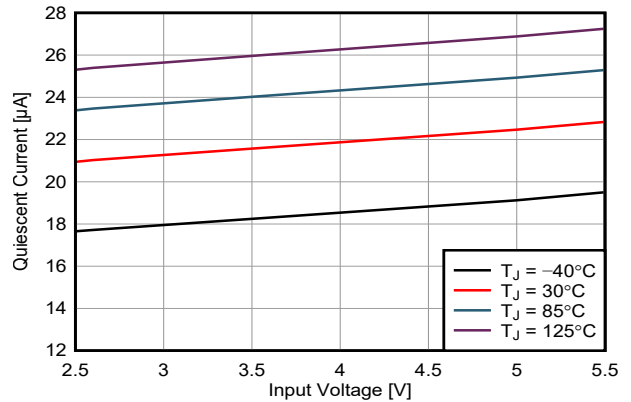
$T_J = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$, $V_{IN} = 2.5\text{ V}$ to 5.5 V . Typical values are at $T_J = 25^{\circ}\text{C}$ and $V_{IN} = 5\text{ V}$ (unless otherwise noted)


PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OUTPUT DISCHARGE					
Output discharge current on SW pin	$V_{IN} = 3\text{ V}$, $V_{OUT} = 2.0\text{ V}$; TPS62A01xDRL		60		mA
Output discharge current on SW pin	$V_{IN} = 3\text{ V}$, $V_{OUT} = 2.0\text{ V}$; TPS62A01xDDC; TPS62A02		76		mA
THERMAL SHUTDOWN					
$T_{J(SD)}$	Thermal shutdown threshold	Temperature rising	170		$^{\circ}\text{C}$
$T_{J(HYS)}$	Thermal shutdown hysteresis		20		$^{\circ}\text{C}$

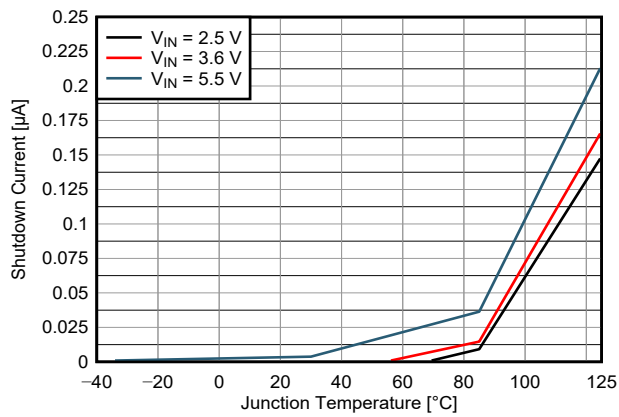
6.6 Typical Characteristics




6-1. Quiescent Current vs Input Voltage (TPS62A01)




6-2. Quiescent Current vs Input Voltage (TPS62A02)



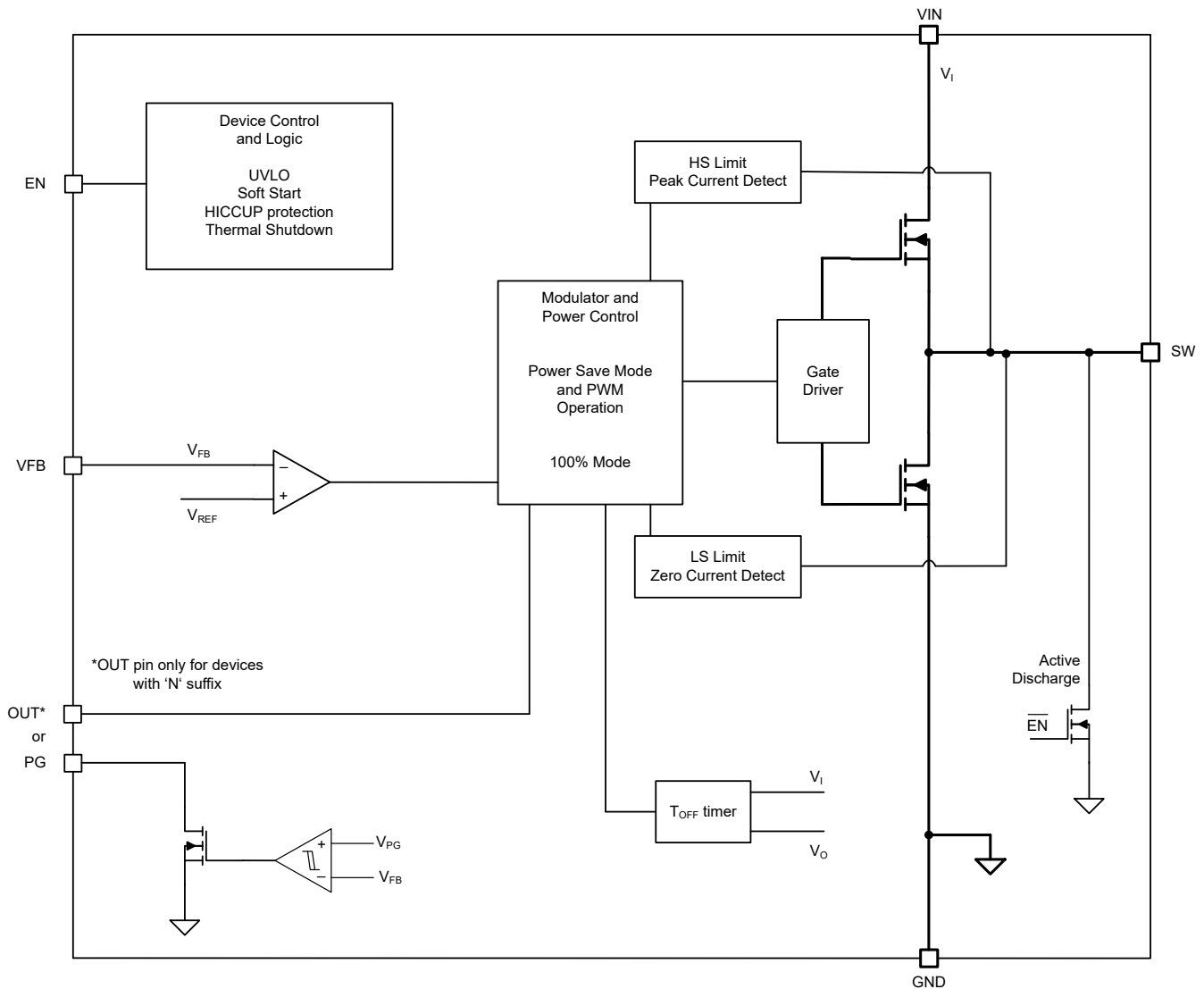

6-3. Shutdown Current vs Junction Temperature

7 Detailed Description

7.1 Overview

The TPS62A0x is a high-efficiency synchronous step-down converter. The device operates with an adaptive off time with a peak current control scheme. The device operates typically at 2.4MHz frequency pulse width modulation (PWM) at moderate to heavy load currents. Based on the V_{IN}/V_{OUT} ratio, a simple circuit sets the required off time for the low-side MOSFET, making the switching frequency relatively constant regardless of the variation of the input voltage, output voltage, and load current.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Power Save Mode

The device automatically enters power save mode to improve efficiency at light load when the inductor current becomes discontinuous. In power save mode, the converter reduces the switching frequency and minimizes current consumption. In power save mode, the output voltage rises slightly above the nominal output voltage. This effect is minimized by increasing the output capacitor or adding a feedforward capacitor.

7.3.2 100% Duty Cycle Low Dropout Operation

The device offers low input-to-output voltage difference by entering 100% duty cycle mode. In this mode, the high-side MOSFET switch is constantly turned on and the low-side MOSFET is switched off. The minimum input voltage to maintain output regulation, depending on the load current and output voltage, is calculated as:

$$V_{IN(MIN)} = V_{OUT} + I_{OUT} \times (R_{DS(ON)} + R_L) \quad (1)$$

where

- $R_{DS(ON)}$ = High-side FET on-resistance
- R_L = Inductor ohmic resistance (DCR)

7.3.3 Soft Start

After enabling the device, internal soft-start circuitry ramps up the output voltage, which reaches the nominal output voltage during start-up time, avoiding excessive inrush current and creating a smooth voltage rise slope. Internal soft-start circuitry also prevents excessive voltage drops of primary cells and rechargeable batteries with high internal impedance.

The TPS62A0x is able to start into a prebiased output capacitor. The converter starts with the applied bias voltage and ramps the output voltage to the nominal value.

7.3.4 Switch Current Limit and Short-Circuit Protection (HICCUP)

The switch current limit prevents the device from high inductor current and drawing excessive current from the battery or input rail. Due to internal propagation delay, the AC peak current can exceed the static current limit during that time. Excessive current can occur with a shorted or saturated inductor, an overload or shorted output circuit condition. If the inductor current reaches the threshold I_{LIM} , the high-side MOSFET is turned off and the low-side MOSFET is turned on to ramp down the inductor current with an adaptive off time.

When this switch current limit is triggered 32 times, the device stops switching to protect the output. The device then automatically starts a new start-up after a typical delay time of 100 μ s has passed. This is named HICCUP short-circuit protection. The device repeats this mode until the high load condition disappears. HICCUP protection is also enabled during the start-up.

7.3.5 Undervoltage Lockout

To avoid misoperation of the device at low input voltages, an undervoltage lockout (UVLO) is implemented, which shuts down the device at voltages lower than V_{UVLO} .

7.3.6 Thermal Shutdown

The device goes into thermal shutdown and stops switching when the junction temperature exceeds T_{JSD} . When the device temperature falls below the threshold by 20°C, the device returns to normal operation automatically.

7.4 Device Functional Modes

7.4.1 Enable and Disable

The device is enabled by setting the EN input to a logic High. Accordingly, a logic Low disables the device. If the device is enabled, the internal power stage starts switching and regulates the output voltage to the set point voltage. The EN input must be terminated and not be left floating.

7.4.2 Power Good

The TPS62A0x (except devices with 'N' suffix) has a built-in power-good (PG) feature to indicate whether the output voltage has reached the target and the device is ready. The PG signal can be used for start-up sequencing of multiple rails. The PG pin is an open-drain output that requires a pullup resistor to any voltage up to the recommended input voltage level. PG is low when the device is turned off due to EN, UVLO (undervoltage lockout), or thermal shutdown. VIN must remain present for the PG pin to stay low. If not used, the power-good

can be tie to GND or left open. The PG indicator has a de-glitch to avoid the signal indicating glitches or transient responses from the loop.

表 7-1. Power-Good indicator Functional Table

Logic Signals				PG Status
V_I	EN Pin	Thermal Shutdown	V_O	
$V_I > UVLO$	HIGH	NO	V_O on target	High Impedance
			$V_O < target$	LOW
		YES	LOW	
	LOW	YES	x	LOW
	LOW	x	x	LOW
$V_I < 1.8V$	x	x	x	Undefined

8 Application and Implementation

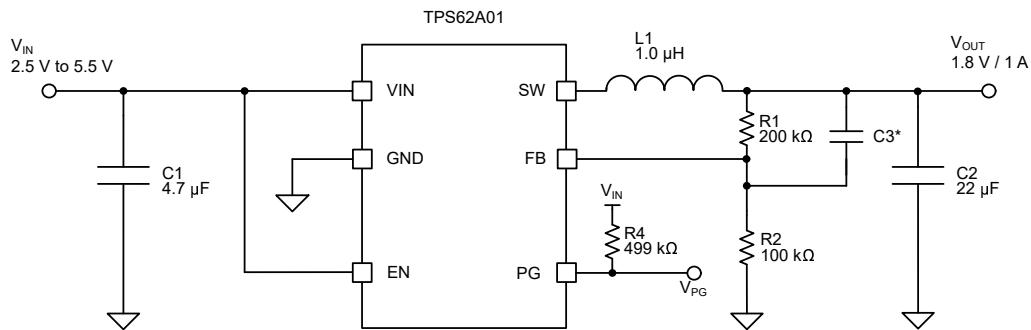
注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

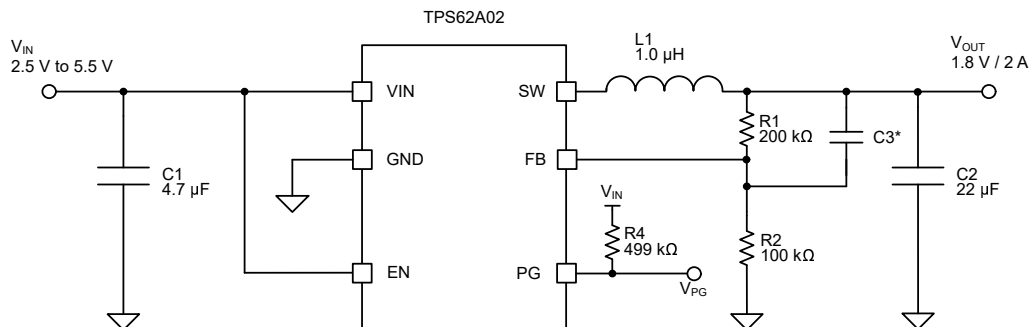
8.1 Application Information

The following section discusses the design of the external components to complete the power supply design for several input and output voltage options by using typical applications as a reference.

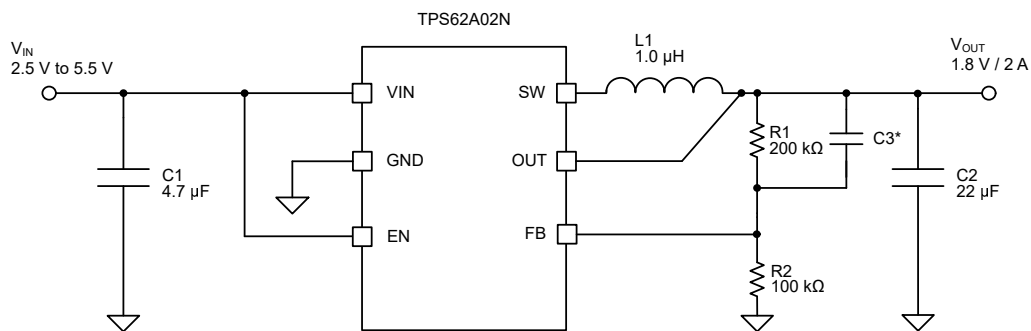
8.2 Typical Application



8-1. TPS62A01 Typical Application Circuit



8-2. TPS62A02 Typical Application Circuit



8-3. TPS62A02N Typical Application Circuit

*C3 is optional

8.2.1 Design Requirements

For this design example, use the parameters listed in 表 8-1 as the input parameters

表 8-1. Design Parameters

Design Parameter	Example Value
Input voltage	2.5V to 5.5V
Output voltage	1.8V
Maximum output current	1.0A, 2.0A

表 8-2 lists the components used for the example.

表 8-2. List of Components

Reference	Description	Manufacturer ⁽¹⁾
C1	4.7μF, Ceramic Capacitor, 10V, X7R, size 0805, GRM21BR71A475KA73L	Murata
C2	22μF, Ceramic Capacitor, 10V, X7R, size 0805, GRM21BZ71A226KE15L	Murata
L1	1μH, Power Inductor, DFE252012F-1R0M (1A) / XGL3520-102MEC (2A)	Murata / Coilcraft
R1, R2	Chip resistor, 1%, size 0603	Std.
C3	Optional, 120pF if needed	Std.

(1) See the *Third-Party Products Disclaimer*.

8.2.2 Detailed Design Procedure

8.2.2.1 Setting the Output Voltage

The output voltage is set by an external resistor divider according to 式 2.

$$R1 = R2 \times \left(\frac{V_{OUT}}{V_{FB}} - 1 \right) = R2 \times \left(\frac{V_{OUT}}{0.6V} - 1 \right) \quad (2)$$

R2 must not be higher than 100kΩ to provide acceptable noise sensitivity.

8.2.2.2 Output Filter Design

The inductor and output capacitor together provide a low-pass filter. To simplify this process, 表 8-3 outlines possible inductor and capacitor value combinations. Checked cells represent combinations that are proven for stability by simulation and lab test. Check further combinations for each individual application.

表 8-3. Matrix of Output Capacitor and Inductor Combinations for TPS62A01 and TPS62A02

V _{OUT} [V]	L [μH] ⁽¹⁾	C _{OUT} [μF] ⁽²⁾		
		10	22	2 × 22
0.6 ≤ V _{OUT} < 1.2	1		+	++ ⁽³⁾
1.2 ≤ V _{OUT} < 1.8			++ ⁽³⁾	+
1.8 ≤ V _{OUT}		+(4)	++ ⁽³⁾	+

(1) Inductor tolerance and current de-rating is anticipated. The effective inductance can vary by +20% and –30%.

(2) Capacitance tolerance and bias voltage de-rating is anticipated. The effective capacitance can vary by +20% and –50%.

(3) This LC combination is the standard value and recommended for most applications.

(4) The minimum C_{OUT} of 10μF does not support an additional feedforward capacitor.

A 0.47μH inductor can also be used with the same recommended output capacitors for the TPS62A02x. In case a lower output ripple is desired, higher output capacitance can help reduce the ripple.

8.2.2.3 Input and Output Capacitor Selection

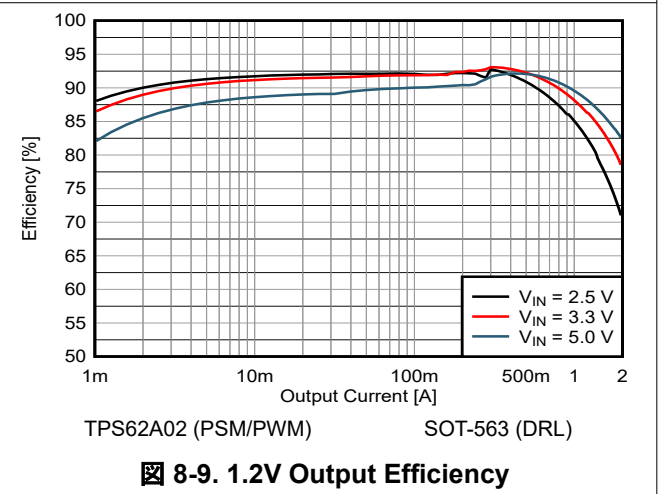
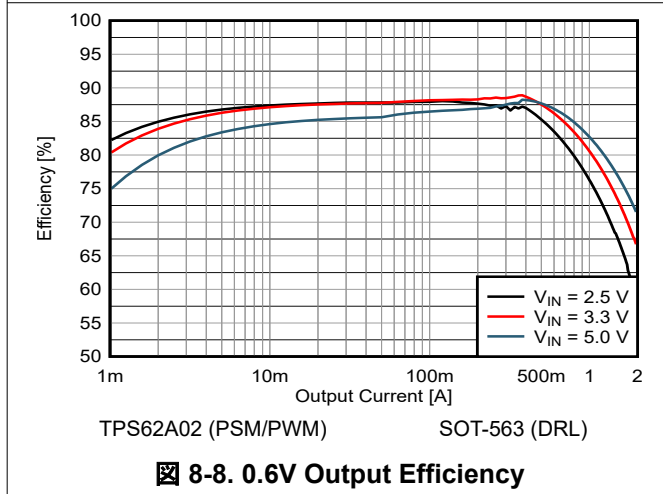
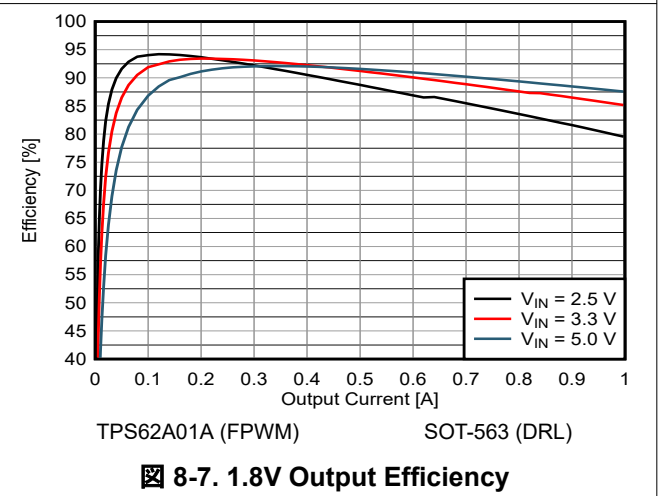
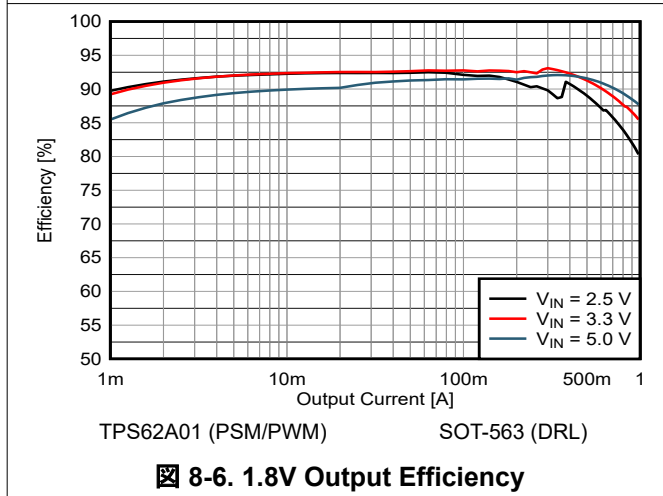
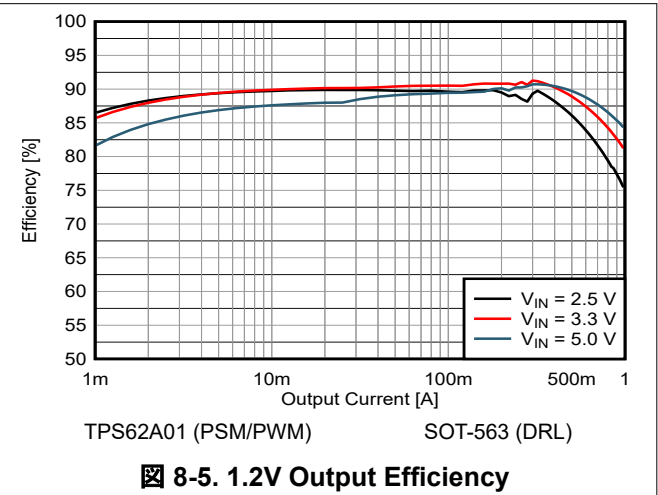
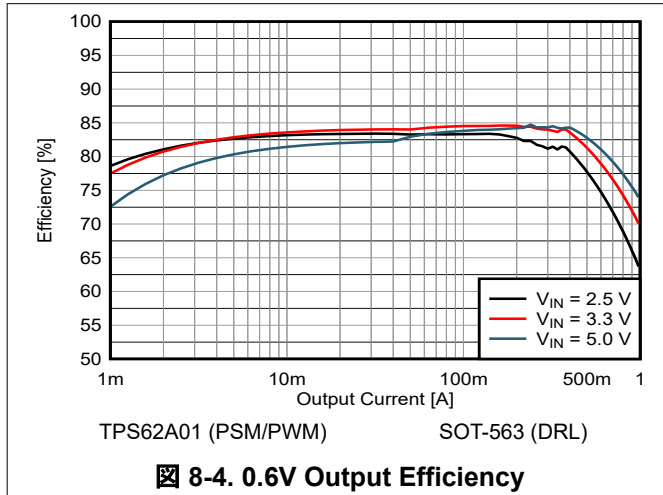
The architecture of the TPS62A0x allows use of tiny ceramic-type output capacitors with low equivalent series resistance (ESR). These capacitors provide low output voltage ripple and are thus recommended. To keep resistance up to high frequencies and to achieve narrow capacitance variation with temperature, TI recommends to use X7R or X5R dielectric.

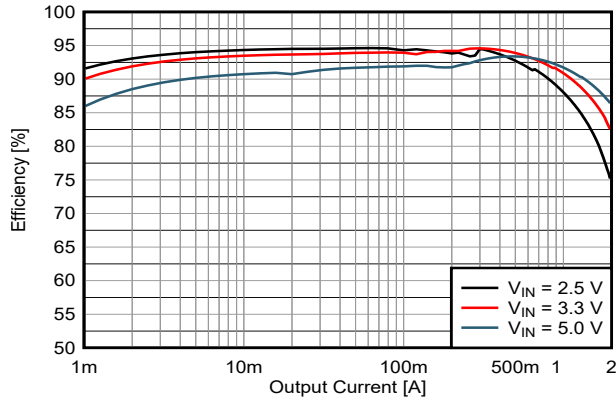
The input capacitor is the low impedance energy source for the converter that helps provide stable operation. TI recommends a low-ESR multilayer ceramic capacitor for best filtering. For most applications, a 4.7 μ F input capacitor is sufficient; a larger value reduces input voltage ripple.

The TPS62A0x is designed to operate with an output capacitor of 10 μ F to 47 μ F, depending on the selected output voltage, as outlined in [表 8-3](#).

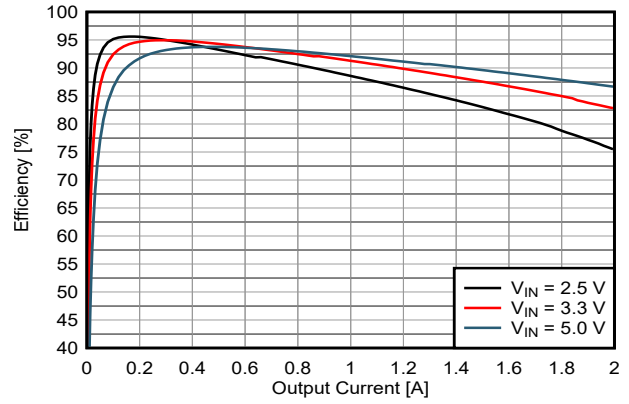
A feedforward capacitor reduces the output ripple in PSM and improves the load transient response. A 120pF capacitor is good for the 1.8V output typical application.

8.2.3 Application Curves

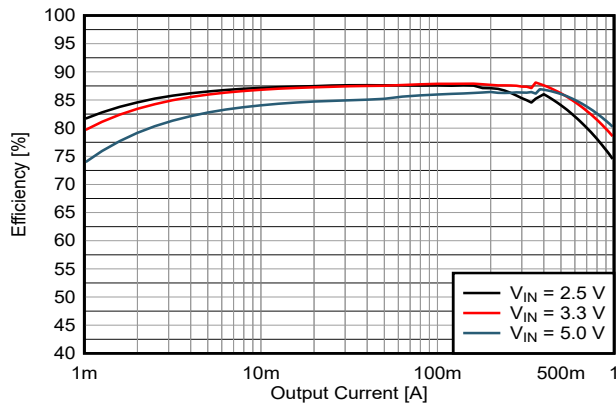




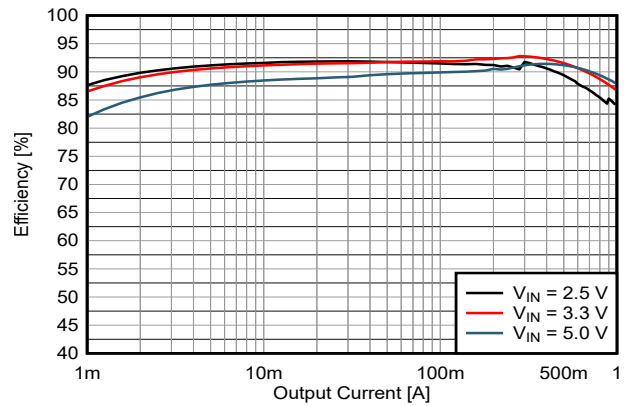
8-10. 1.8V Output Efficiency



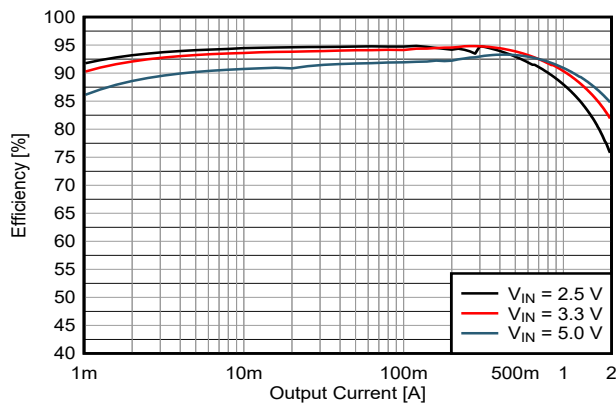
8-11. 1.8V Output Efficiency



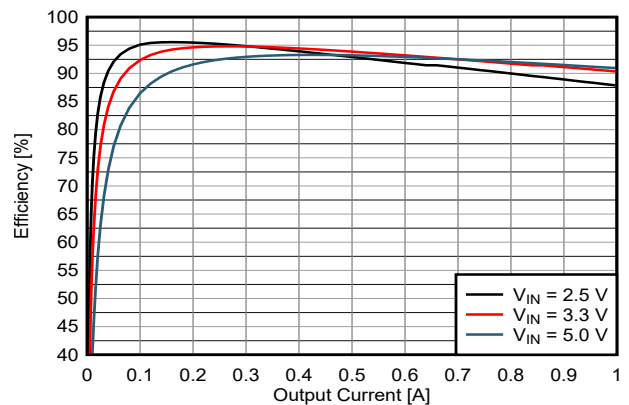
8-12. 0.6V Output Efficiency



8-13. 1.2V Output Efficiency



8-14. 1.8V Output Efficiency



8-15. 1.8V Output Efficiency

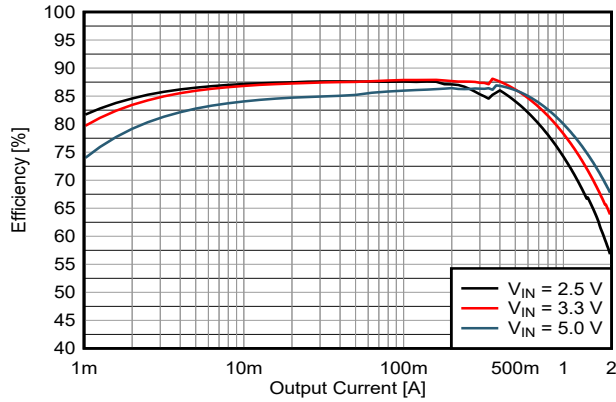


図 8-16. 0.6V Output Efficiency

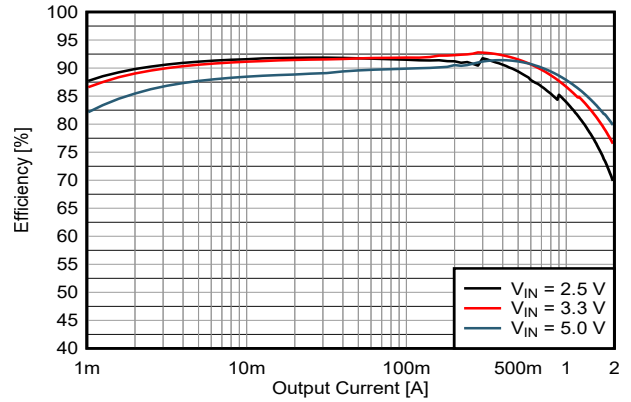


図 8-17. 1.2V Output Efficiency

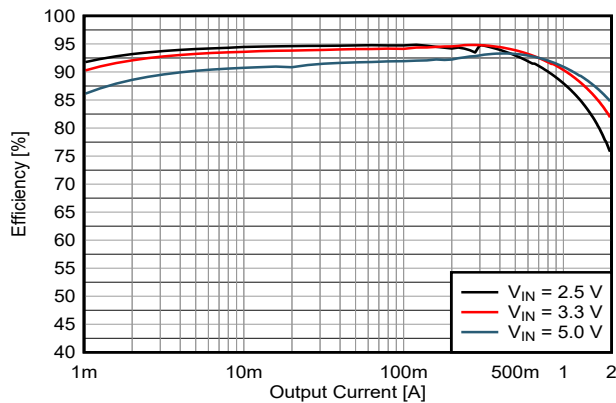


図 8-18. 1.8V Output Efficiency

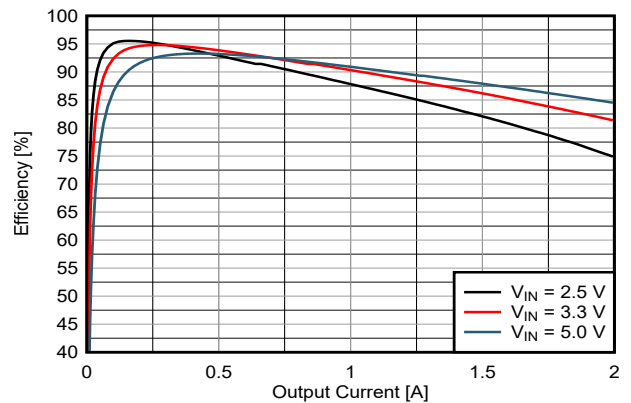


図 8-19. 1.8V Output Efficiency

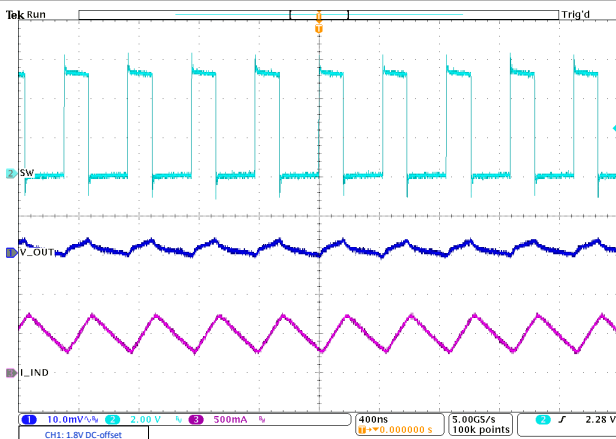


図 8-20. PWM Operation

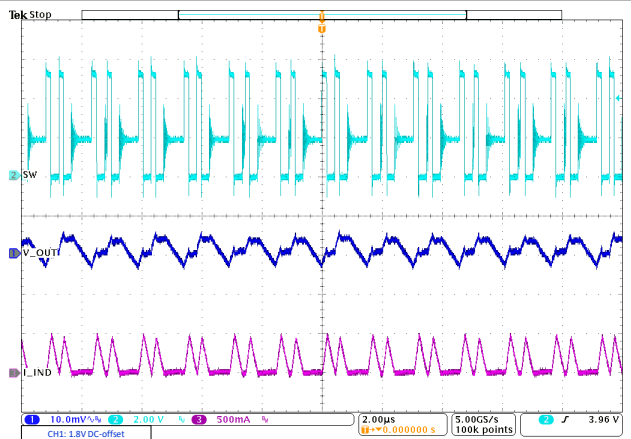
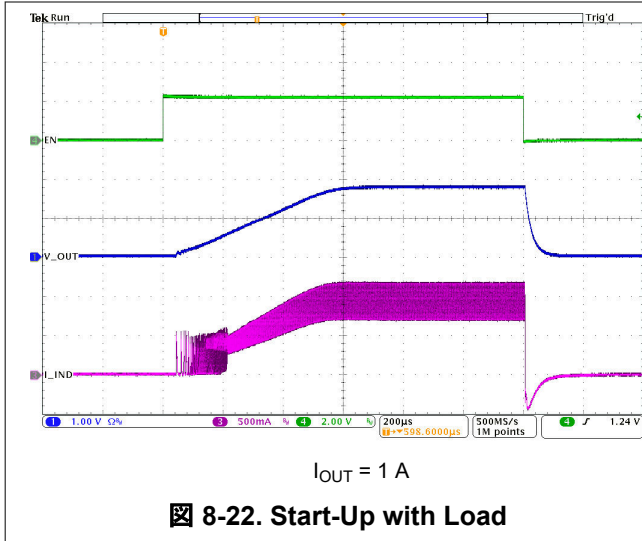


図 8-21. Power Save Mode Operation



8.3 Power Supply Recommendations

The device is designed to operate from an input voltage supply range from 2.5V to 5.5V. Make sure that the input power supply has a sufficient current rating for the application.

8.4 Layout

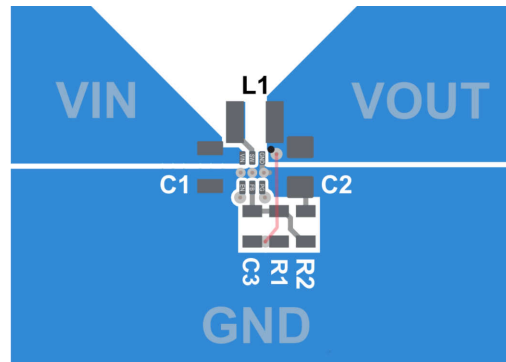
8.4.1 Layout Guidelines

The printed-circuit-board (PCB) layout is an important step to maintain the high performance of the TPS62A01x and TPS62A02x devices.

- Place the input and output capacitors and the inductor as close as possible to the IC. This action keeps the power traces short. Routing these power traces direct and wide results in low trace resistance and low parasitic inductance.
- Connect the low side of the input and output capacitors properly to the GND pin to avoid a ground potential shift.
- The sense traces connected to FB is a signal trace. Take special care to avoid noise being induced. Keep these traces away from SW nodes.
- Use a common ground. GND layers can be used for shielding.

See [8-24](#) and [8-25](#) for the recommended PCB layout.

8.4.2 Layout Example



8-24. TPS62A0x (SOT563) PCB Layout Recommendation

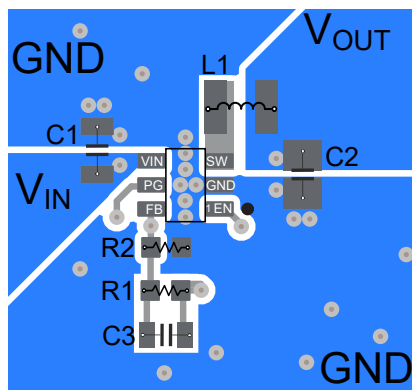


図 8-25. TPS62A0x (SOT23-6) PCB Layout Recommendation

9 Device and Documentation Support

9.1 Device Support

9.1.1 サード・パーティ製品に関する免責事項

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9.2 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、www.tij.co.jp のデバイス製品フォルダを開いてください。[通知] をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取ることができます。変更の詳細については、改訂されたドキュメントに含まれている改訂履歴をご覧ください。

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9.6 用語集

テキサス・インスツルメンツ用語集

この用語集には、用語や略語の一覧および定義が記載されています。

10 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision D (April 2024) to Revision E (June 2024)	Page
<ul style="list-style-type: none"> • Changed device status of TPS62A02Nx versions and devices in DDC package from preview to production throughout the data sheet..... 	3

Changes from Revision C (December 2023) to Revision D (April 2024)	Page
<ul style="list-style-type: none"> • データシート全体にわたって接尾辞「N」のあるデバイスを追加..... • Changed absolute maximum voltage of VIN, EN and PG from 6V to 6.5V..... • Updated block diagram to include devices with 'N' suffix (OUT instead of PG)..... 	1 4 8

Changes from Revision B (July 2022) to Revision C (December 2023)	Page
<ul style="list-style-type: none"> • Added DDC package option throughout the data sheet..... • Changed ESD Ratings CDM row from showing testing was per JESD22-C101 to show that testing was per JS-002..... • Changed block diagram PG circuit by swapping V_{PG} and V_{FB} 	3 4 8

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPS62A01ADRLR	Active	Production	SOT-5X3 (DRL) 6	4000 LARGE T&R	Yes	Call TI Sn	Level-1-260C-UNLIM	-40 to 125	1J8
TPS62A01ADRLR.A	Active	Production	SOT-5X3 (DRL) 6	4000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	1J8
TPS62A01APDDCR	Active	Production	SOT-23- THIN (DDC) 6	3000 LARGE T&R	Yes	Call TI Sn	Level-1-260C-UNLIM	-40 to 125	A01AP
TPS62A01APDDCR.A	Active	Production	SOT-23- THIN (DDC) 6	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	A01AP
TPS62A01DRLR	Active	Production	SOT-5X3 (DRL) 6	4000 LARGE T&R	Yes	Call TI Sn	Level-1-260C-UNLIM	-40 to 125	1J7
TPS62A01DRLR.A	Active	Production	SOT-5X3 (DRL) 6	4000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	1J7
TPS62A01PDDCR	Active	Production	SOT-23- THIN (DDC) 6	3000 LARGE T&R	Yes	Call TI Sn	Level-1-260C-UNLIM	-40 to 125	A01P
TPS62A01PDDCR.A	Active	Production	SOT-23- THIN (DDC) 6	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	A01P
TPS62A02ADRLR	Active	Production	SOT-5X3 (DRL) 6	4000 LARGE T&R	Yes	Call TI Sn	Level-1-260C-UNLIM	-40 to 125	1JM
TPS62A02ADRLR.A	Active	Production	SOT-5X3 (DRL) 6	4000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	1JM
TPS62A02APDDCR	Active	Production	SOT-23- THIN (DDC) 6	3000 LARGE T&R	Yes	Call TI Sn	Level-1-260C-UNLIM	-40 to 125	A02AP
TPS62A02APDDCR.A	Active	Production	SOT-23- THIN (DDC) 6	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	A02AP
TPS62A02DRLR	Active	Production	SOT-5X3 (DRL) 6	4000 LARGE T&R	Yes	Call TI Sn	Level-1-260C-UNLIM	-40 to 125	1JL
TPS62A02DRLR.A	Active	Production	SOT-5X3 (DRL) 6	4000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	1JL
TPS62A02NADRLR	Active	Production	SOT-5X3 (DRL) 6	4000 LARGE T&R	Yes	Call TI Sn	Level-1-260C-UNLIM	-40 to 125	1SC
TPS62A02NADRLR.A	Active	Production	SOT-5X3 (DRL) 6	4000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	1SC
TPS62A02NDRLR	Active	Production	SOT-5X3 (DRL) 6	4000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	1SB
TPS62A02NDRLR.A	Active	Production	SOT-5X3 (DRL) 6	4000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	1SB
TPS62A02PDDCR	Active	Production	SOT-23- THIN (DDC) 6	3000 LARGE T&R	Yes	Call TI Sn	Level-1-260C-UNLIM	-40 to 125	A02P
TPS62A02PDDCR.A	Active	Production	SOT-23- THIN (DDC) 6	3000 LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 125	A02P

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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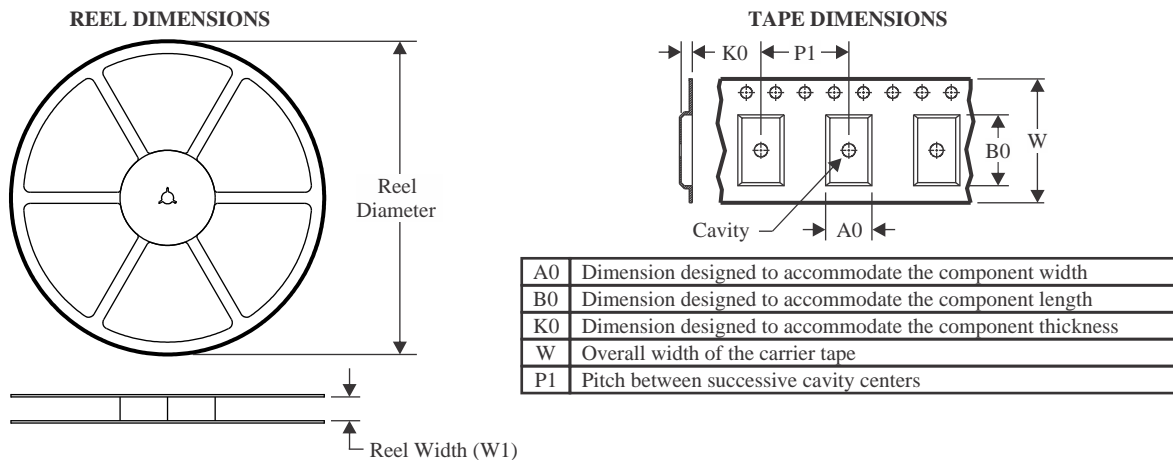
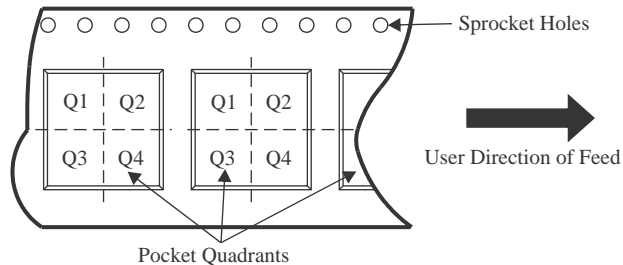
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF TPS62A01, TPS62A01A, TPS62A02, TPS62A02A :

- Automotive : [TPS62A01-Q1](#), [TPS62A01A-Q1](#), [TPS62A02-Q1](#), [TPS62A02A-Q1](#)

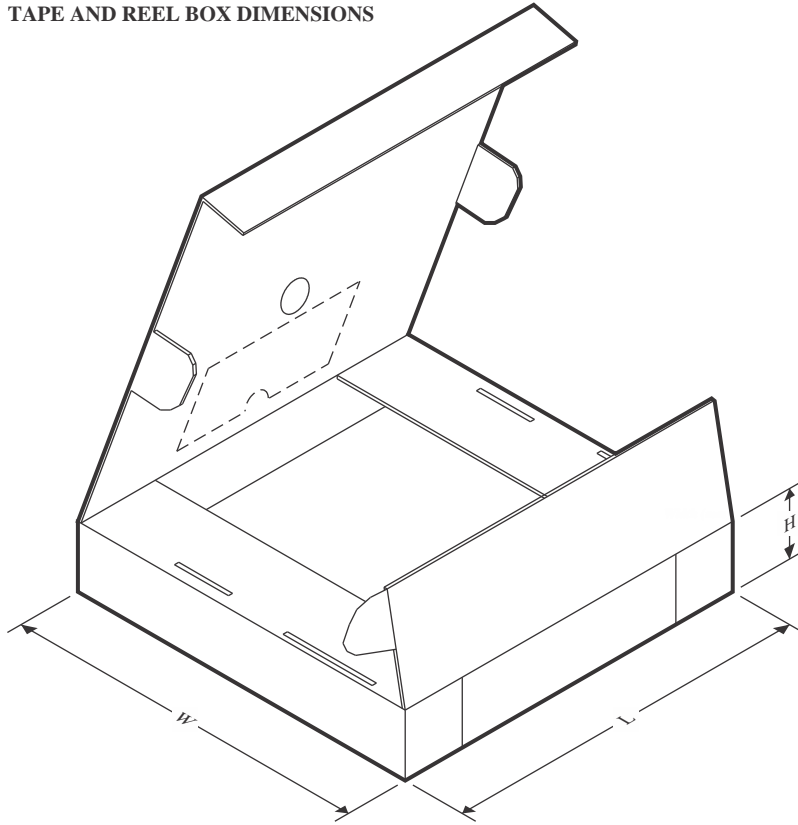
NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS62A01ADRLR	SOT-5X3	DRL	6	4000	180.0	8.4	2.0	1.8	0.75	4.0	8.0	Q3
TPS62A01APDDCR	SOT-23-THIN	DDC	6	3000	180.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS62A01DRLR	SOT-5X3	DRL	6	4000	180.0	8.4	2.0	1.8	0.75	4.0	8.0	Q3
TPS62A01PDDCR	SOT-23-THIN	DDC	6	3000	180.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS62A02ADRLR	SOT-5X3	DRL	6	4000	180.0	8.4	2.0	1.8	0.75	4.0	8.0	Q3
TPS62A02APDDCR	SOT-23-THIN	DDC	6	3000	180.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TPS62A02DRLR	SOT-5X3	DRL	6	4000	180.0	8.4	1.8	1.8	0.75	4.0	8.0	Q3
TPS62A02DRLR	SOT-5X3	DRL	6	4000	180.0	8.4	2.0	1.8	0.75	4.0	8.0	Q3
TPS62A02NADRLR	SOT-5X3	DRL	6	4000	180.0	8.4	2.0	1.8	0.75	4.0	8.0	Q3
TPS62A02NDRLR	SOT-5X3	DRL	6	4000	180.0	8.4	2.0	1.8	0.75	4.0	8.0	Q3
TPS62A02PDDCR	SOT-23-THIN	DDC	6	3000	180.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS62A01ADRLR	SOT-5X3	DRL	6	4000	210.0	185.0	35.0
TPS62A01APDDCR	SOT-23-THIN	DDC	6	3000	210.0	185.0	35.0
TPS62A01DRLR	SOT-5X3	DRL	6	4000	210.0	185.0	35.0
TPS62A01PDDCR	SOT-23-THIN	DDC	6	3000	210.0	185.0	35.0
TPS62A02ADRLR	SOT-5X3	DRL	6	4000	210.0	185.0	35.0
TPS62A02APDDCR	SOT-23-THIN	DDC	6	3000	210.0	185.0	35.0
TPS62A02DRLR	SOT-5X3	DRL	6	4000	210.0	185.0	35.0
TPS62A02DRLR	SOT-5X3	DRL	6	4000	210.0	185.0	35.0
TPS62A02NADRLR	SOT-5X3	DRL	6	4000	210.0	185.0	35.0
TPS62A02NDRLR	SOT-5X3	DRL	6	4000	210.0	185.0	35.0
TPS62A02PDDCR	SOT-23-THIN	DDC	6	3000	210.0	185.0	35.0

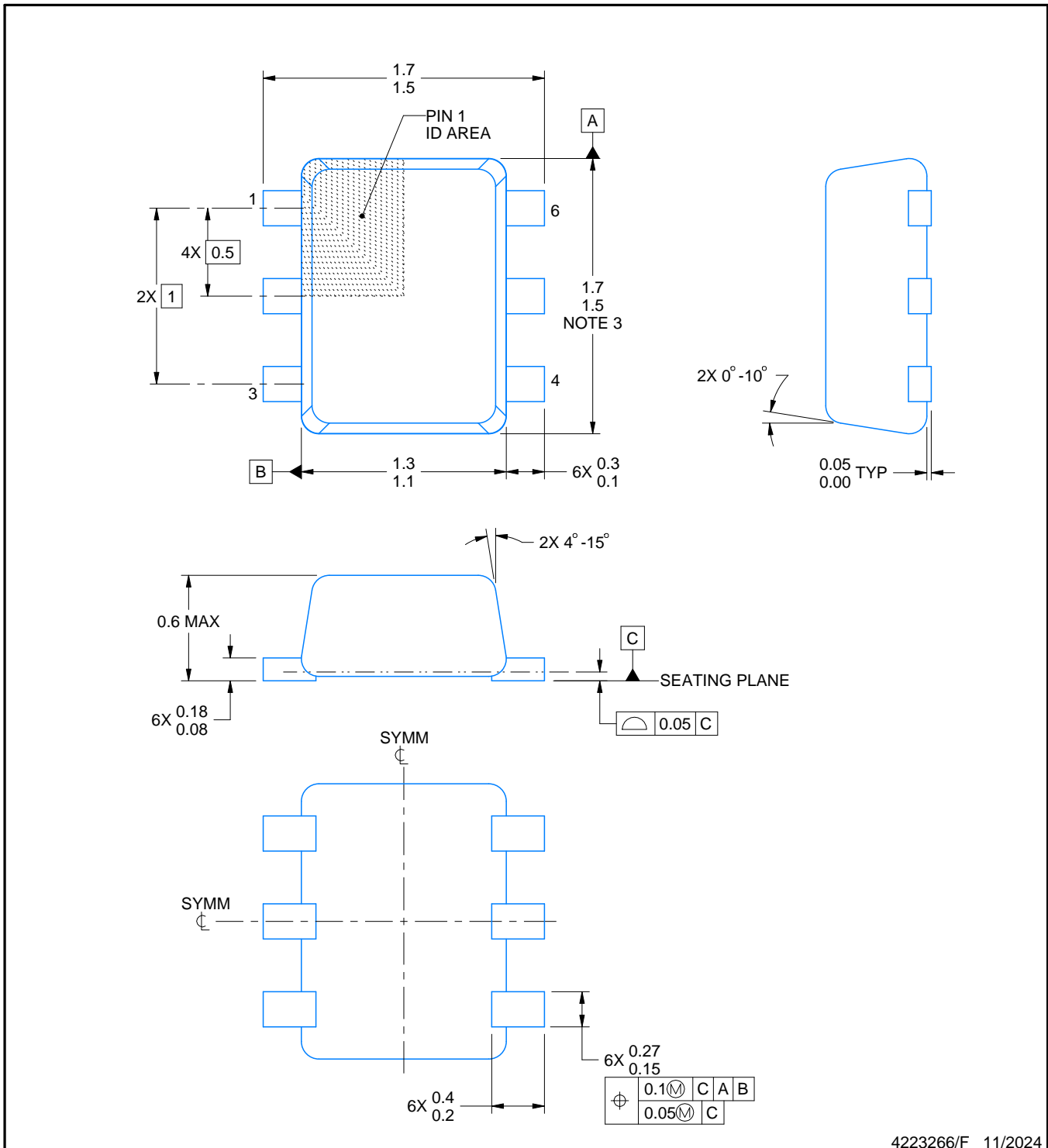
DRL0006A



PACKAGE OUTLINE

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



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NOTES:

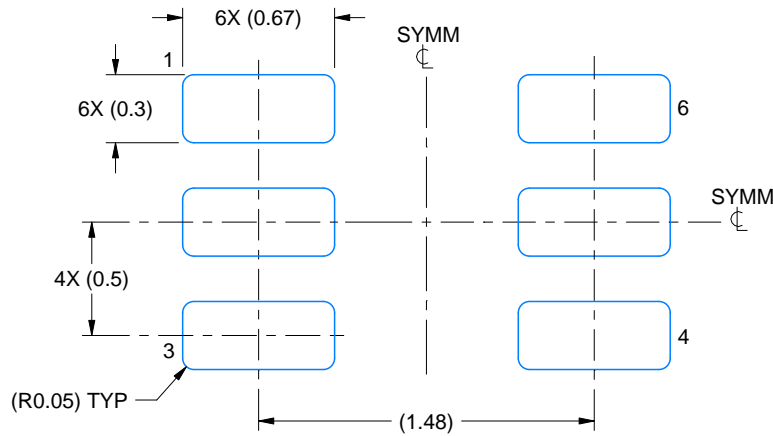
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-293 Variation UAAD

EXAMPLE BOARD LAYOUT

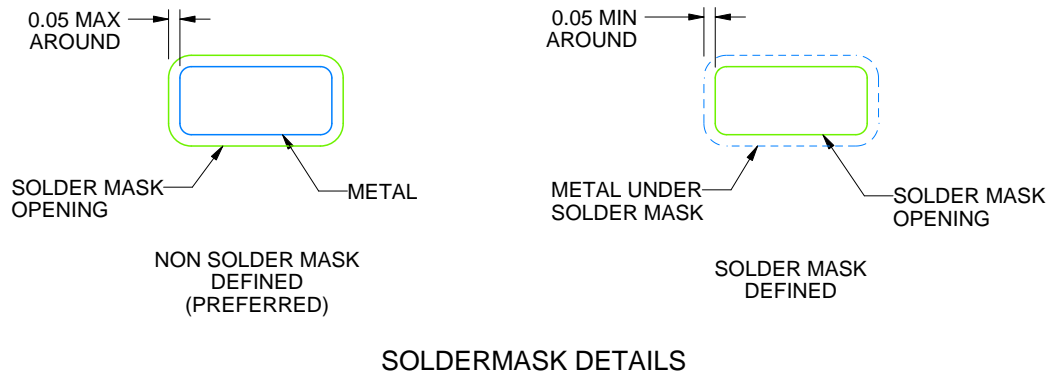
DRL0006A

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



LAND PATTERN EXAMPLE
SCALE:30X



SOLDERMASK DETAILS

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NOTES: (continued)

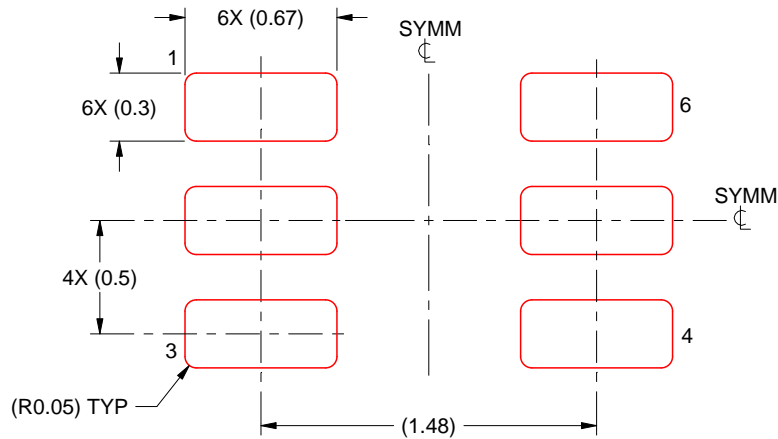
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
7. Land pattern design aligns to IPC-610, Bottom Termination Component (BTC) solder joint inspection criteria.

EXAMPLE STENCIL DESIGN

DRL0006A

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:30X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

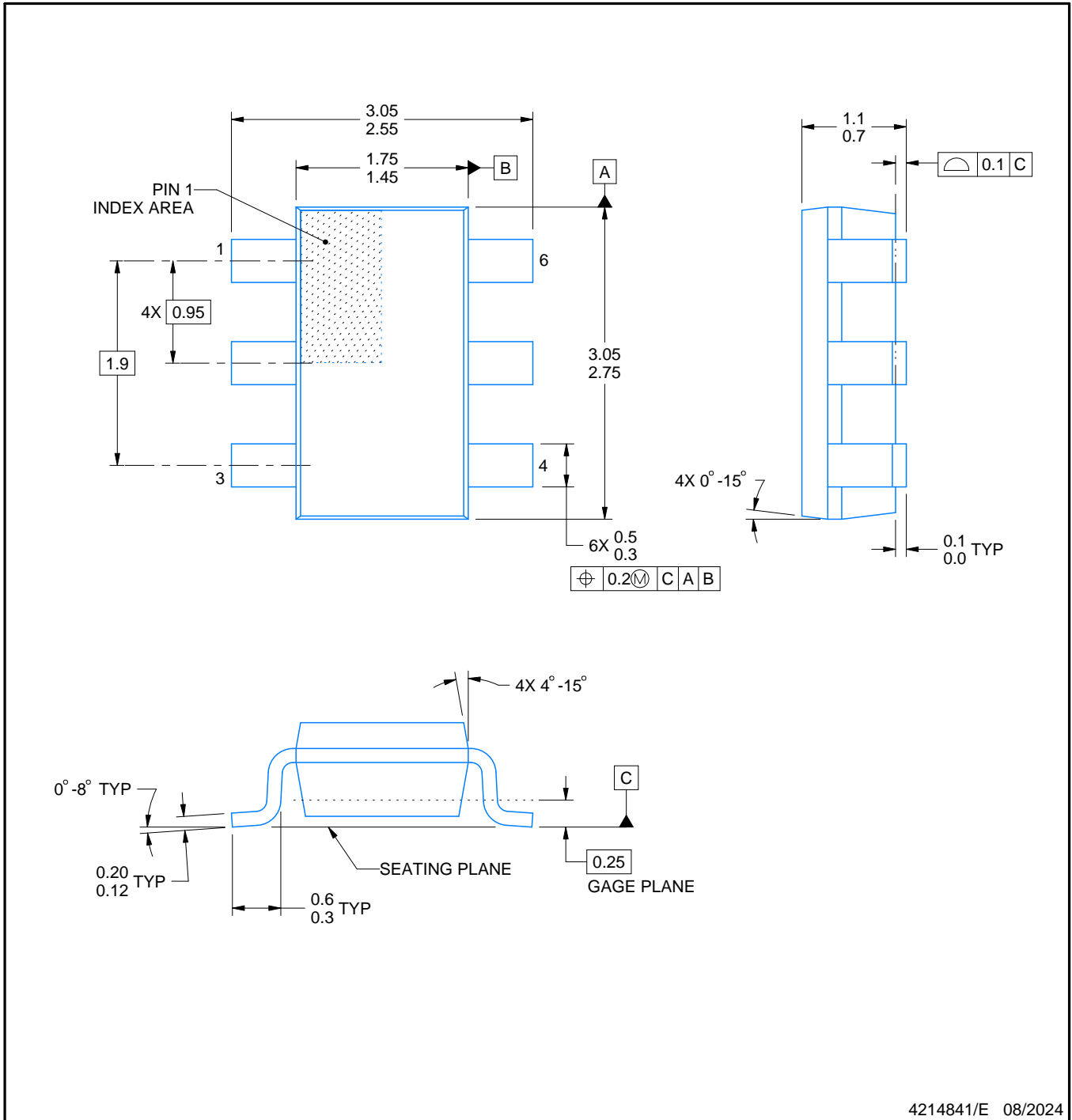
DDC0006A



PACKAGE OUTLINE

SOT-23 - 1.1 max height

SMALL OUTLINE TRANSISTOR



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NOTES:

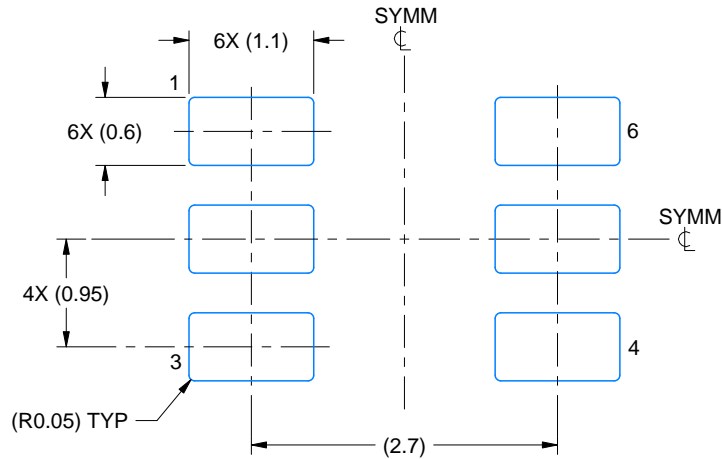
- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. Reference JEDEC MO-193.

EXAMPLE BOARD LAYOUT

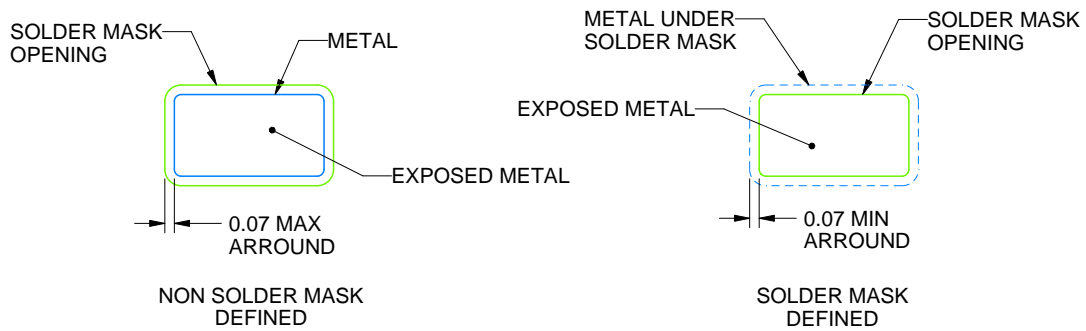
DDC0006A

SOT-23 - 1.1 max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE
EXPLODED METAL SHOWN
SCALE:15X



SOLDEMASK DETAILS

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NOTES: (continued)

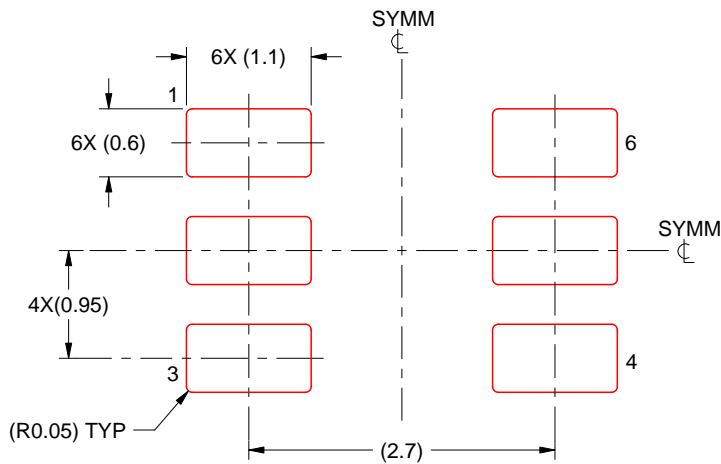
- 4. Publication IPC-7351 may have alternate designs.
- 5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DDC0006A

SOT-23 - 1.1 max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE
BASED ON 0.125 THICK STENCIL
SCALE:15X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
7. Board assembly site may have different recommendations for stencil design.

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